

ABSTRACT

A sink compound laminate modeling process having a copper material in thickness of 0.1~0.8 mm placed at the bottom of the modeling cavity with the bottom of the copper laminate fully bound to the bottom of the modeling cavity, the copper being heated up to 300~650°C, and melting aluminum being filled into the modeling cavity using gravity casting process to create diffused lamination to the interface between the copper and aluminum materials, melting aluminum being cooled and cured to avail an integrated compound laminate in a given profile of heterogeneous copper and aluminum.

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